ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES International and Pan-American Co	burn, Illinois, All rights	reserved under both	This docume level parts, th	ent is a declaration entite decl	on of the subst ncompasses all	ances within the manufa l lower level materials fo	cturer listed or which the 1	item. Note: i nanufacture	f the item is an as has engineering	sembly with lowe responsibility.	
IPC Web Site for Information on Inttp://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and				Ifg Informat	ion		
Supplier Information											
mpany name* Company unique ID			I	Unique ID Authority				Response Date*			
onsemi	ni							2023-06-06			
Contact Name	Title - Contact]	Phone - Contact*			Email -	Email - Contact*				
Product-Env-Stewards	ewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
uthorized Representative* Title - Representative]	Phone - Representative*				Email - Representative*			
Product-Env-Stewards	Compliance		NA			Produ	Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Iten	n Number Mfr Ite	Iumber Mfr Item Name		Effective Date	Version	Manufacturing Site	Manufacturing Site		UOM	Unit Type	
SZMME	IBZ6V8ALT3G ZEN SOT23 REG .225W		L	2023-06-06		CN1		8.02	mg	Each	
Manufacturing Proccess Information				·							
Terminal Plating / Grid Array Material	Terminal Base Alloy J-STD-0		SL Rating	Peak Proce	Peak Process Body Temperature		eak Tempera	Temperature Number of Reflow Cycles		eles	
Matte Tin (Sn) - annealed CU Alloy 1		1		260	C	30	secon	nds 3			
Comments											
evel 1 - maximum time at peak temperature during so	Idering is 10-30 second	ds									
or more information regarding material composition	please refer to page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.05	mg	Supplier	Silicon (Si)	7440-21-3		0.05	mg	
Lead Frame 2.9	2.92	mg	В	Nickel (Ni)	7440-02-0		1.06	mg	
			Supplier	Iron (Fe)	7439-89-6		1.4658	mg	
			Supplier	Copper (Cu)	7440-50-8		0.3942	mg	
Mold Compound-Black	4.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.49	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.0245	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7105	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		3.185	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.49	mg	
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg	
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg	